

LOW LOOP HEIGHT BALL BONDING METHOD AND APPARATUS

ABSTRACT

In accordance with the invention, a bump is formed on top of a die bond pad by forming a ball bond there. Then, without severing the wire, the capillary undergoes a set of coordinated motions to fold the wire on top of the ball bond. The wire is then bonded on top of the ball bond bump without severing the wire. This is then followed by a further set of coordinated xy motions to form the loop and bring the capillary over the second bond site (e.g., on the lead frame). The wire is then stitch bonded to the second bond site and the tail severed to complete the wire loop interconnect.

Figure 3